



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC067N06LS3 G		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001250992						
<b>Package</b>		PG-TDSON-8-14		<b>Weight*</b>		101.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.81	1.81	18062	18062
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		96	
	non noble metal	zinc	7440-66-6	0.039	0.04		383	
	non noble metal	iron	7439-89-6	0.778	0.77		7658	
wire	non noble metal	copper	7440-50-8	31.590	31.10	31.92	310959	319096
	non noble metal	copper	7440-50-8	0.058	0.06	0.06	574	574
	encapsulation	organic material	carbon black	1333-86-4	0.236	0.23		2325
plastics	plastics	epoxy resin	-	7.322	7.21		72074	
	inorganic material	silicondioxide	60676-86-0	39.680	39.04	46.48	390596	464995
	leadfinish	non noble metal	tin	7440-31-5	1.243	1.22	12231	12231
plating	noble metal	silver	7440-22-4	0.037	0.04	0.04	368	368
solder	noble metal	silver	7440-22-4	0.046	0.05		453	
	non noble metal	tin	7440-31-5	0.037	0.04		362	
	non noble metal	lead	7439-92-1	1.758	1.73	1.82	17301	18116
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.02		167	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		50	
	non noble metal	copper	7440-50-8	16.898	16.63	16.65	166341	166558
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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